

VERSION WITH MARKINGS TO SHOW CHANGES MADE 09/973,002

IN THE CLAIMS:

Proposed Claim Amendment:

1. (Twice Amended) A semiconductor device comprising:

a substrate having a first plurality of pads and a second plurality of pads;

a first semiconductor chip mounted on said substrate and having a third plurality of pads;

a plate member arranged on said first semiconductor chip and having an [a first] end at an inward position of said first semiconductor chip adjacent [from] to the third plurality of pads[, and a second end being exposed to an outside of a seal member through a side surface thereof];

a second semiconductor chip arranged on said plate member and having a fourth plurality of pads;

a first structure and a second structure respectively and electrically interconnecting said third plurality of pads [of said first semiconductor chip] with said first plurality of pads [of said substrate] and said fourth plurality of pads [of said second semiconductor chip] with said second plurality of pads [of said substrate]; and

a [the] seal member sealing said first semiconductor chip, said plate member and said second semiconductor chip[.] and having a seal member side surface;

wherein said plate member has a first portion covered by said first and second semiconductor chips, and a second portion protruding from said first and second semiconductor chips and extending through said seal member to the seal member side surface whereby said plate

member is exposed to an outside of said seal member.

2. (Amended) A semiconductor device according to claim 1, wherein said first structure and said second structure [electrically connecting said third plurality of pads of said first semiconductor chip and said fourth plurality of pads of said second semiconductor chip respectively to said first plurality of pads of said first semiconductor chip and said fourth plurality of pads of said second semiconductor chip respectively to said first plurality of pads and said second plurality of pads of said substrate by] are made of bonding wires.

5. (Twice Amended) A semiconductor device according to claim 1, wherein said plate member includes a fifth plurality of pads [and a sixth plurality of pads, a third structure and a fourth], part of said second structure [respectively and] electrically inter-connecting [said third plurality of pads of said first semiconductor chip with said first plurality of pads of said substrate and] part of said fourth plurality of pads [of said second semiconductor chip] with part of said second [first] plurality of pads [of said substrate] via said fifth plurality of pads. [;

wherein a first member electrically connecting said fourth plurality of pads of said second semiconductor chip with said sixth plurality of pads of said plate member and a second member electrically connecting said fifth plurality of pads plate member with said second plurality of pads.]